



Full Material Declaration for attached parts list

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Declarations authorised by:
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Declaration effective from: 05 March 2019 [Approved on 21 February 2025, 14:10 GMT]

Materials and substances

Use/Location	Material Group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Chip (die)	Other inorganic materials	89.61%	ALUMINUM, ELEMENTAL	7429-90-5	0.35%
			Elemental silicon	7440-21-3	99.65%
Die attach	Other nonferrous metals	0.07%	4,4'-Sulfonylbisbenzamine	80-08-0	1%
			1,4-BIS(2,3-EPOXYPROPOXY)BUTANE	2425-79-8	7%
			Formaldehyde, polymer with (chloromethyl)oxirane and phenol	9003-36-5	15%
			Silver	7440-22-4	77%
Encapsulation	EP (Epoxy resin)	7.71%	Carbon black	1333-86-4	1%
			2,2-Bis(4(2',3'-epoxypropoxy)phenyl)propane	1675-54-3	5%
			Epoxy resin 89	26335-32-0	10%
			Silicon Dioxide	7631-86-9	10%
			Quartz sand	60676-86-0	74%
Inner preparation	Copper (e.g. copper amounts in cable harnesses)	0.34%	PALLADIUM, ELEMENTAL	7440-05-3	3%
			COPPER, ELEMENTAL	7440-50-8	97%
Leadframe	Copper (e.g. copper amounts in cable harnesses)	2.27%	Elemental silicon	7440-21-3	1.2%
			NICKEL, ELEMENTAL REACH Article 67 Exemption	7440-02-0	2%
			COPPER, ELEMENTAL	7440-50-8	96.8%

Attached parts list

Part number	Part name	Part Mass	Part Mass UoM
SOT-883_Pb & H-Free Cu	Diode / Transistor SMD	0.000882	g

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Materials and substances

Use/Location	Material Group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Chip (die)	Other inorganic materials	1.28%	Silicon	7440-21-3	100%
Die attach	Other nonferrous metals	1.28%	Oxirane, 2,2'-[1,4-butanediylbis(oxyethylene)]bis-	2425-79-8	5%
			Epoxy resin 89	26335-32-0	30%
			Silver	7440-22-4	65%
Encapsulation	EP (Epoxy resin)	76.42%	Carbon black	1333-86-4	0.3%
			2,2-Bis(4(2',3'-epoxypropoxy)phenyl)propane	1675-54-3	4%
			Epoxy resin 89	26335-32-0	9%
			Silicon Dioxide	7631-86-9	9.7%
			Quartz sand	60676-86-0	77%
Inner preparation	Gold	0.46%	Gold	7440-57-5	100%
Leadfinish	Nickel and Nickel alloys	0.53%	GOLD, ELEMENTAL	7440-57-5	1.21%
			PALLADIUM, ELEMENTAL	7440-05-3	7.51%
			NICKEL, ELEMENTAL REACH Article 67 Exemption	7440-02-0	91.28%
Leadframe	Copper (e.g. copper amounts in cable harnesses)	20.03%	MAGNESIUM, ELEMENTAL	7439-95-4	0.296%
			Elemental silicon	7440-21-3	1.184%
			NICKEL, ELEMENTAL REACH Article 67 Exemption	7440-02-0	4.145%
			COPPER, ELEMENTAL	7440-50-8	94.375%

Attached parts list

Part number	Part name	Part Mass	Part Mass UoM
SOT-883_Pb & H-Free	Diode / Transistor SMD	0.000861	g

